PDM: Rev:M

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form no. 7530-001-103

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	PRODUCT NUMBER	DIM A	BOARD OFFSE DIM C	T DIM D	PACK	ING				<u>'</u>							
	10014747-001	47.20±0.10	0	2.85±0.0	5			-			48.55±0.15 			-			
	10014747-002	47.20±0.10	0.3	2.85±0.0	5				•		46.35±0.15			 -			
	10014747-003	47.20±0.10	0.6	2.85±0.0	5 SEE NO				4		43.7±0.1						
	10014747-004	46.70±0.10	0	2.85±0.0	- FOR DE 5 DESCRI	ETATL PTION		A	•		0.635 *67=42.		OTE 2	_			
	10014747-006	46.70±0.10	0	2.75±0.0					-		0.033 *01-42						
	10014747-007	47.20±0.10	-0.3	2.85±0.0	5		15				 	2	1.27				
Ī		20±0.10 (-001~-003,005 6.70±0.10 (-004,-006)	(LEAD FF	EE PLATING, S	EE NOTE 7)		30±0.						0.35±0.0				
	10014747-XXXLF 47	20±0.10 (-001~-003,005 6.70±0.10 (-004,-006)	(LEAD FF	EE PLATING, S	EE NOTE 7)		5.3	!	2			CL OF	DATUM A	- - - -			
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								5.00±0 2.00±0	-	0.45±0. 0.08					6	. 40±0.	
																- 1	
									5.08 3.810 3.810								
Д				NOTE:	TEDIAL.				38.10						SCALE 1.5	1.500	00 A
$\stackrel{\sim}{\dashv}$				I. MATERIAL: CONTACT: PHBR 0.12† CONTACT: PHBR 0.12† CONTACT: PHBR 0.12†													
				GROUND SHIELD: BRASS 0.15† HOUSING: LCP UL 94V-0, BLACK 2. FINISH:													
۱٦/			CO	NTACT: ALL						Au or GXT	PLATI	NG 0.38 M	ICRON; M				
•				SOLDER TAIL TIN LEAD 2.5 MICRON. GROUND SHIELD: ALL OVER NI UNDER I.27 MICRON; CONTACT Au or GXT PLATING 0.38 MICRON; ∕M∕ SOLDER TAIL TIN LEAD 3.8 MICRON.													
	COPLANARITY		4. MA	TED CONNEC	TOR SHO	ULD BE	BASED	ON IS 0.Im ON JEIDA	AND PCMCI	A SPECIFICATIO	Ν.						
	0.10E			- X	XX USE TRA	Y PACKA	GE 1872	PCS		iS-14-920)							
		4111		- X	XXT USE TA XXS USE TR	AY PACK	AGF 200	PCS	/ CARTON.								
			-XXXA USE TAPE AND REEL 600 PCS / REEL. 6. ELIMINATE THE CORNER TO PREVENT INTERFERENCE WITH SOLDER TAIL.														
	0	FFSET + Y OFFSET	-	7. LEAD FREE PLATING: FOR CONTACT TAIL: NI UNDER PLATING 0.5 MICRON, TIN 2.5 MICRON; FOR GROUND SHIELD TAIL: NI UNDER PLATING 1.27 MICRON, TIN 3.8 MICRON.													
		E		8. PR	ODUCT SPEC	. REFER	TO GS-	12-22	8.		IVES AND OTHER		RY				
		DIM C		R	EGULATIONS	AS DES	CRIBLED	IN G	S-22-008		TEMPERATURE F			N IR-REFLO	WC		
	(BOARE	OFFSET)		mat'l c	ode				tolerances u		CUSTOMER		EC)				1
	SECTION A-A SCALE 5.000			Itr	Itr ecn no.		date		otherwise specified .X±0.3		COPY	FSJ			www.fcicor	nect.com	
				М		Ĭ.	linea		.XX±0.13		projection	title 68P CARDBUS				1	
								angles	. XXX± 0°±	=0.05 =2°				PTACLE		Υ	
								dr engr	KENNY TAI	10/03/102	- MM	produ	uct family dwg no		PCMCIA	code	
t		RIGINALLY CREATEI						chr	KENNY TAI	10/03/102	scale . 000	A	1 -) 474	47 t	sheet	1
	ENGINEER ENVIRONMET THIS FILE MUST BE I	NT AND ANY FUTURE	E REVISIONS T	Shee	t revisio	n		appd	PAUL WANG	10/03/102	1.000	+		, , <u>, , , , , , , , , , , , , , , , , </u>	' '		-
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